NOTES:
1. MATERIAL:
   SHIELD & CONTACTS: COPPER ALLOY
   HOUSING: UL 94V-0, HIGH TEMPERATURE THERMOPLASTIC.
   COLOR: SEE PRODUCT NUMBER CODE
2. PLATING: SEE PRODUCT NUMBER CODE
   SHIELD: BRIGHT TIN, NICKEL UNDERPLATE (USED FOR WAVE SOLDER PROCESS),
   PLATING NICKEL ONLY (USED FOR PI PROCESS).
3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
4. RECOMMENDED BOARD THICKNESS IS 1.57 mm (.062)
5. PACKING STANDARD CS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
6. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND
   OTHER COUNTRY REGULATION AS DESCRIBED IN CS-22-008
7. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C
   PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR
   PHASE REFLOW OVEN.
8. THE PART CAN BE USED FOR PI PROCESS.